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IN THE CLAIMS:

1. (original) An assembly comprising
a substrate,
an integrated circuit device adapted to be electrically and
mechanically attached to the substrate,
electrically conductive connecting elements between the
device and the substrate that electrically connect the device and
the substrate, and
at least one adhesive body positioned between the integrated
circuit device and the substrate to form a mechanical connection
between the circuit device and the substrate,
said at least one adhesive body comprising a non-
thermosetting material which, when heated, releases said
mechanical connection to allow removal of the circuit device from
the substrate.
2. (original) The assembly as set forth in claim 1 wherein
said non-thermosetting material comprises a thermoplastic
polymer.
3. (original) The assembly as set forth in claim 2 wherein
said thermoplastic polymer has a bonding temperature of at least
about 100 degrees Celsius.
4. (original) The assembly as set forth in claim 2 wherein
said thermoplastic polymer has a bonding temperature of less than
about 300 degrees Celsius.
5. (original) The assembly as set forth in claim 1 wherein
said at least one adhesive body is positioned at a peripheral
edge of the integrated circuit device.

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6. (original) The assembly as set forth in claim 5 wherein said circuit device has corners and the adhesive bodies are located at said corners.

7. (original) The assembly as set forth in claim 1 wherein said at least one adhesive body has a substantially spherical shape.

8. (original) The assembly as set forth in claim 1 wherein said at least one adhesive body comprises four adhesive bodies.

9. (original) The assembly as set forth in claim 1 wherein said integrated circuit device is a chip package.

10. (original) The assembly as set forth in claim 1 wherein said integrated circuit device is a multi-chip module.

11. (original) The assembly as set forth in claim 1 wherein said integrated circuit device has a bottom surface with four corners and said at least one adhesive body is located approximately equidistant from adjacent corners in contact with the bottom surface of the circuit device.

12. (original) An assembly comprising
a substrate,
an integrated circuit device adapted to be electrically and mechanically attached to the substrate,
5 electrically conductive connecting elements between the device and the substrate that electrically connect the device and the substrate, and
at least two adhesive bodies comprising a non-thermosetting material positioned between the integrated circuit device and the

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10 substrate to form a releasable mechanical connection between the circuit device and the substrate.

13. (original) The assembly as set forth in claim 12 wherein said releasable mechanical connection is released by heating said adhesive bodies.

14. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies are spaced apart to form an open space between the adhesive bodies.

15. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies are positioned at a periphery of the integrated circuit device.

16. (original) The assembly as set forth in claim 12 wherein said integrated circuit device has corners and the at least two adhesive bodies comprise four adhesive bodies positioned at said corners.

17. (original) The assembly as set forth in claim 12 wherein said at least two adhesive bodies comprise a thermoplastic polymer.

Claims 18-24. (Cancelled)